



# HS-3182

March 1997

## ARINC 429 Bus Interface Line Driver Circuit

### Features

- TTL and CMOS Compatible Inputs
- Adjustable Rise and Fall Times via Two External Capacitors
- Programmable Output Differential Voltage via  $V_{REF}$  Input
- Operates at Data Rates Up to 100 Kilobits/Sec
- Output Short Circuit Proof and Contains Over-Voltage Protection
- Outputs are Inhibited (0 Volts) If DATA (A) and DATA (B) Inputs are Both in the "Logic One" State
- DATA (A) and DATA (B) Signals are "AND'd" with Clock and Sync Signals
- Full Military Temperature Range

### Ordering Information

PACKAGE	TEMPERATURE RANGE	PART NUMBER	PKG. NO
SBDIP	-40°C to +85°C	HS1-3182-9+	D16.3
	-55°C to +125°C	HS1-3182-8	D16.3
	-55°C to +125°C	5962-8687901EA	D16.3
CLCC	-55°C to +125°C	HS4-3182-8	J28.A
	-55°C to +125°C	5962-86879013A	J28.A

### Description

The HS-3182 is a monolithic dielectrically isolated bipolar differential line driver designed to meet the specifications of ARINC 429. This Device is intended to be used with a companion chip, HS-3282 CMOS ARINC Bus Interface Circuit, which provides the data formatting and processor interface function.

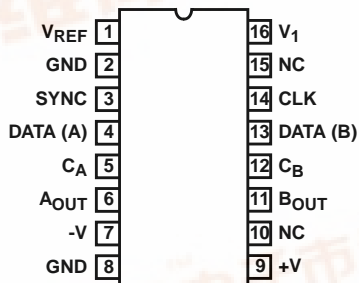
All logic inputs are TTL and CMOS compatible. In addition to the DATA (A) and DATA (B) inputs, there are also inputs for CLOCK and SYNC signals which are AND'd with the DATA inputs. This feature enhances system performance and allows the HS-3182 to be used with devices other than the HS-3182.

Three power supplies are necessary to operate the HS-3182:  $+V = +15V \pm 10\%$ ,  $-V = -15V \pm 10\%$ , and  $V_1 = 5V \pm 5\%$ .  $V_{REF}$  is used to program the differential output voltage swing such that  $V_{OUT} (DIFF) = \pm 2V_{REF}$ . Typically,  $V_{REF} = V_1 = 5V \pm 5\%$ , but a separate power supply may be used for  $V_{REF}$  which should not exceed 6V.

The driver output impedance is  $75\Omega \pm 20\%$  at 25°C. Driver output rise and fall times are independently programmed through the use of two external capacitors connected to the  $C_A$  and  $C_B$  inputs. Typical capacitor values are  $C_A = C_B = 75pF$  for high-speed operation (100KBPS), and  $C_A = C_B = 300pF$  for low-speed operation (12 to 14.5KBPS). The outputs are protected against over-voltage and short circuit as shown in the Block Diagram. The HS-3182 is designed to operate with a case temperature range of -55°C to +125°C, or 0°C to +70°C.

### Pinouts

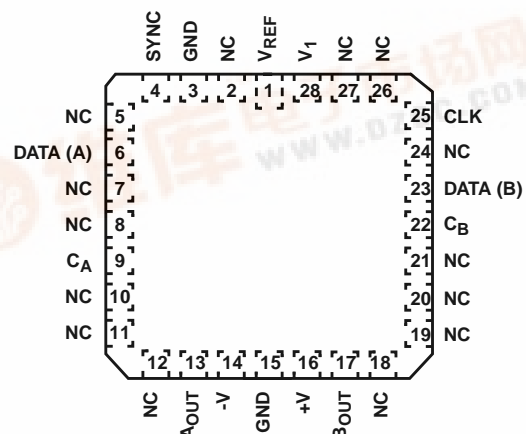
HS-3182 (SBDIP)  
TOP VIEW



TRUTH TABLE

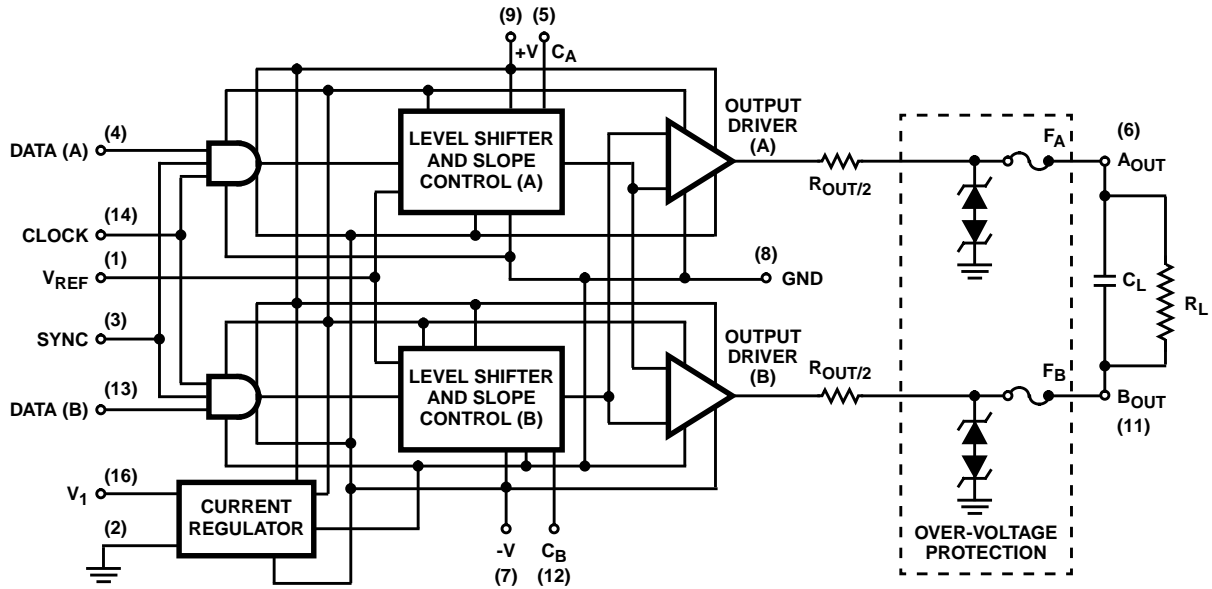
SYNC	CLK	DATA (A)	DATA (B)	AOUT	BOUT	COMMENTS
X	L	X	X	0V	0V	Null
L	X	X	X	0V	0V	Null
H	H	L	L	0V	0V	Null
H	H	L	H	-VREF	+VREF	Low
H	H	H	L	+VREF	-VREF	High
H	H	H	H	0V	0V	Null

HS-3182 (CLCC)  
TOP VIEW

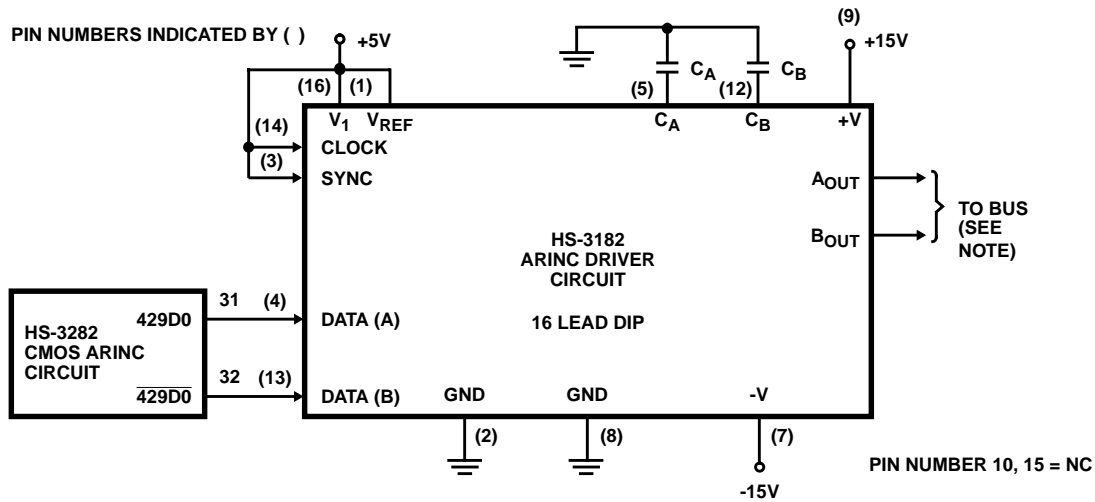


## HS-3182

### Block Diagram



### Typical Application



NOTE: The rise and fall time of the outputs are set to ARINC specified values by  $C_A$  and  $C_B$ . Typical  $C_A = C_B = 75pF$  for high speed and  $300pF$  for low speed operation. The output HI and low levels are set to ARINC specifications by  $V_{REF}$ .

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### Absolute Maximum Ratings

Voltage Between +V and -V Terminals	40V
V <sub>1</sub>	7V
V <sub>REF</sub>	6V
Logic Input Voltage	GND -0.3V to V <sub>1</sub> +0.3V
ESD Classification	Class 1
Output Short Circuit Duration	See Note 1
Output Over-Voltage Protection	See Note 2

### Recommended Operating Conditions

Operating Voltage	
+V	+15V ± 10%
-V	-15V ± 10%
V <sub>1</sub>	.5V ± 5%
V <sub>REF</sub> (For ARINC 429)	.5V ± 5%
Operating Temperature Range	
HS-3182-5	0°C to +70°C
HS-3182-8	-55°C to +125°C

#### NOTES:

- Heat sink may be required for 100K bits/s at +125°C and output short circuit at +125°C.
- The fuses used for output over-voltage protection may be blown by a fault at each output of greater than ± 6.5V relative to GND.

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Thermal Information

Thermal Resistance (Typical)	$\theta_{JA}$	$\theta_{JC}$
SBDIP Package	75°C/W	18°C/W
CLCC Package	60°C/W	14°C/W
Storage Temperature Range	-65°C to +150°C	
Maximum Junction Temperature	+175°C	
Maximum Lead Temperature (Soldering 10s)	+300°C	

### Die Characteristics

Transistor Count	133
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### DC Electrical Performance Specifications

DC PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	MIN	MAX	UNITS
Supply Current +V (Operating)	I <sub>CCOP</sub> (+V)	No Load (0-100K bits/s)	-	16	mA
Supply Current -V (Operating)	I <sub>CCOP</sub> (-V)	No Load (0-100K bits/s)	-16	-	mA
Supply Current V <sub>1</sub> (Operating)	I <sub>CCOP</sub> (V <sub>1</sub> )	No Load (0-100K bits/s)	-	975	μA
Supply Current V <sub>REF</sub> (Operating)	I <sub>CCOP</sub> (V <sub>REF</sub> )	No Load (0-100K bits/s)	-1.0	-	mA
Logic "1" Input Voltage	V <sub>IH</sub>		2.0	-	V
Logic "0" Input Voltage	V <sub>IL</sub>		-	0.5	V
Output Voltage High (Output to GND)	V <sub>OH</sub>	No Load (0-100K bits/s)	V <sub>REF</sub> (-250mV)	V <sub>REF</sub> (+250mV)	
Output Voltage Low (Output to GND)	V <sub>OL</sub>	No Load (0-100K bits/s)	-V <sub>REF</sub> (-250mV)	-V <sub>REF</sub> (+250mV)	
Output Voltage Null	V <sub>NULL</sub>	No Load (0-100K bits/s)	-250	+250	mV
Input Current (Input Low)	I <sub>IL</sub>		-20	-	μA
Input Current (Input High)	I <sub>IH</sub>		-	10	μA
Output Short Circuit Current (Output High)	I <sub>OHSC</sub>	Short to GND	-	-80	mA
Output Short Circuit Current (Output Low)	I <sub>OLSC</sub>	Short to GND	80	-	mA
Output Impedance	Z <sub>O</sub>	T <sub>A</sub> = +25°C	60	90	Ω

#### NOTE:

- +V = +15V ± 10%, -V = -15V ± 10%, V<sub>1</sub> = V<sub>REF</sub> = 5V ± 5%, unless otherwise specified T<sub>A</sub> = 0°C to +70°C for HS-3182-5 and T<sub>A</sub> = -55°C to +125°C for HS-3182-8.

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### AC Electrical Performance Specifications

AC PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	MIN	MAX	UNITS
Rise Time (A <sub>OUT</sub> , B <sub>OUT</sub> )	t <sub>R</sub>	C <sub>A</sub> = C <sub>B</sub> = 75pF, Note 2	1	2	μS
		(at T <sub>A</sub> = -55°C Only)	0.9	2.4	μS
		C <sub>A</sub> = C <sub>B</sub> = 300pF, Note 2	3	9	μS
Fall Time (A <sub>OUT</sub> , B <sub>OUT</sub> )	t <sub>F</sub>	C <sub>A</sub> = C <sub>B</sub> = 75pF, Note 3	1	2	μS
		(at T <sub>A</sub> = -55°C Only)	0.9	2.4	μS
		C <sub>A</sub> = C <sub>B</sub> = 300pF, Note 3	3	9	μS
Propagation Delay Input to Output	t <sub>PLH</sub>	C <sub>A</sub> = C <sub>B</sub> = 75pF, No Load	-	3.3	μS
Propagation Delay Input to Output	t <sub>PHL</sub>	C <sub>A</sub> = C <sub>B</sub> = 75pF, No Load	-	3.3	μS

#### NOTES:

- +V = +15V, -V = -15V, V<sub>1</sub> = V<sub>REF</sub> = 5V, unless otherwise specified T<sub>A</sub> = 0°C to +70°C for HS-3182-5 and T<sub>A</sub> = -55°C to +125°C for HS-3182-8.
- t<sub>R</sub> measured 50% to 90% times 2, no load.
- t<sub>F</sub> measured 50% to 10% times 2, no load.

### Electrical Performance Specifications

PARAMETER	SYMBOL	(NOTE 1) CONDITIONS	MIN	MAX	UNITS
Input Capacitance	C <sub>IN</sub>	T <sub>A</sub> = +25°C	-	15	pF
Supply Current +V (Short Circuit)	I <sub>SC</sub> (+V)	Short to GND, T <sub>A</sub> = +25°C	-	150	mA
Supply Current -V (Short Circuit)	I <sub>SC</sub> (-V)	Short to GND, T <sub>A</sub> = +25°C	-150	-	mA

#### NOTE:

- The parameters listed in Table 3 are controlled via design or process parameters and are not directly tested. These parameters are characterized upon initial design and after major process and/or design changes affecting these parameters.

### Power Specifications

Nominal Power at +25°C, +V = +15V, -V = -15V, V<sub>1</sub> = V<sub>REF</sub> = 5V, Notes 1, 3

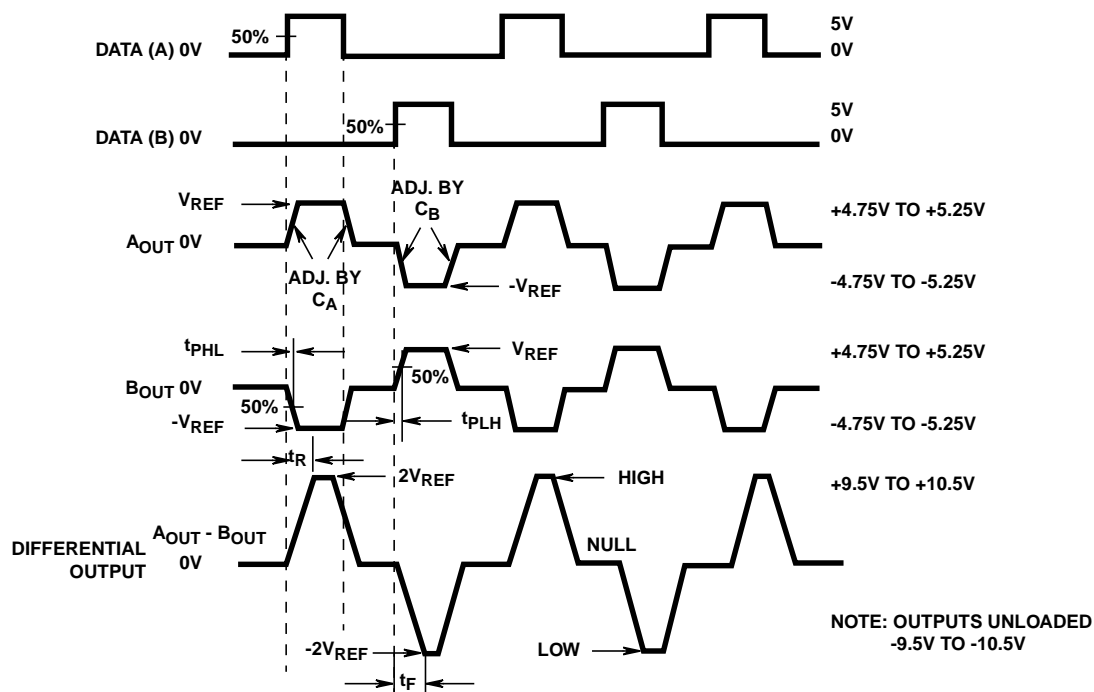
DATA RATE (K BITS/s)	LOAD	+V	V-	V <sub>1</sub>	CHIP POWER	POWER DISSIPATION IN LOAD
0-100	No Load	11mA	-10mA	600μA	325mW	0
12.5-14	Full Load, Note 2	24mW	-24mW	600μA	660mW	60mW
100	Full Load, Note 2	46mW	-46mW	600μA	1 Watt	325mW

#### NOTES:

- Heat sink may be required for 100K bits/s at +125°C and output short circuit at +125°C.  
Thermal characteristics: T<sub>(CASE)</sub> = T<sub>(Junction)</sub> - θ<sub>(Junction - Case)</sub> P<sub>(Dissipation)</sub>  
Where: T<sub>(Junction Max)</sub> = +175°C  
θ<sub>(Junction - Case)</sub> = 10.9°C/W (6.1°C/W for LCC)  
θ<sub>(Junction - Ambient)</sub> = 73.5°C/W (54.0°C/W for LCC)
- Full Load for ARINC 429: R<sub>L</sub> = 400Ω and C<sub>L</sub> = 30,000pF in parallel between A<sub>OUT</sub> and B<sub>OUT</sub> (see block diagram).
- Output Over-Voltage Protection: The fuses used for output over-voltage protection may be blown by a fault at each output of greater than ±6.5V relative to GND.

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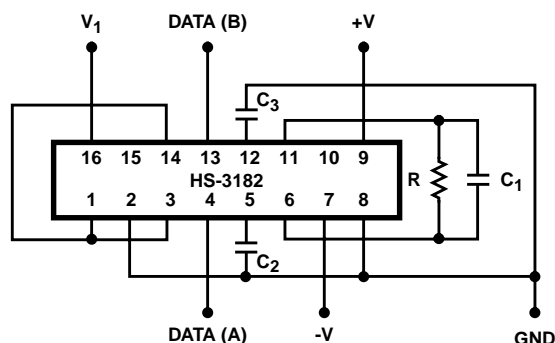
### Driver Waveforms



NOTES:  $t_R$  measured 50% to 90% times 2  
 $t_F$  measured 50% to 10% times 2  
 $V_{IH} = 5V$   $V_{OL} = -4.75V$  to  $-5.25V$   
 $V_{IL} = 0V$   $V_{OH} = 4.75V$  to  $5.25V$

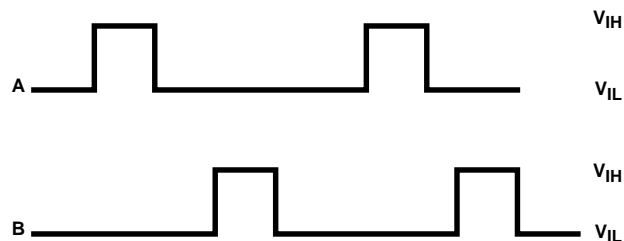
When the Data (A) input is in the Logic One state and the Data (B) input is in the Logic Zero state,  $A_{OUT}$  is equal to  $V_{REF}$  and  $B_{OUT}$  is equal to  $-V_{REF}$ . This constitutes the Output High state. Data (A) and Data (B) both in the Logic Zero state causes both  $A_{OUT}$  and  $B_{OUT}$  to be equal to  $0V$  which designates the output Null state. Data (A) in the Logic Zero state and Data (B) in the Logic One state causes  $A_{OUT}$  to be equal to  $-V_{REF}$  and  $B_{OUT}$  to be equal to  $V_{REF}$  which is the Output Low state.

### Burn-In Schematic



NOTES:  $R = 400\Omega \pm 5\%$   
 $C_1 = 0.03\mu F \pm 20\%$   
 $C_2 = C_3 = 500pF$ , NPO  
 $+V = +15.5V \pm 0.5V$   
 $-V = -15.5V \pm 0.5V$   
 $V_1 = +5.5V \pm 0.5V$

A  $0.0\mu F$  decoupling capacitor is required on each of the three supply lines ( $+V$ ,  $-V$  and  $V_1$ ) at every 3rd Burn-In socket.



Ambient Temp. Max. =  $+125^{\circ}C$ .

Package = 16 Lead Side Brazed DIP.

Pulse Conditions = A & B =  $6.25kHz \pm 10\%$ . B is delayed one-half cycle and in sync with A.

$V_{IH} = 2.0V$  Min.

$V_{IL} = 0.5V$  Max.

## HS-3182

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